

#### PDS-271



# CTF-RJ45

### APPLICATIONS

- + 10BASE-T
- + 100BASE-T
- + 1000BASE-T
- + 10GBASE-T

#### FEATURES AND BENEFITS

- + Standard contacts and connectors
- + Extend a 1000BASE-T communication line up to 120km
- + Simple integration
- + Low power consumption: 1-2 Watts
- + Reduce system weight with fiber optics
- + Small form factor
- + Virtually eliminates any EMI/RFI interference

#### RUGGEDIZATION

- + Industry standard rugged transmitters and receivers -40°C to +85°C
- + PCB securely mounted within chassis

#### OVERVIEW

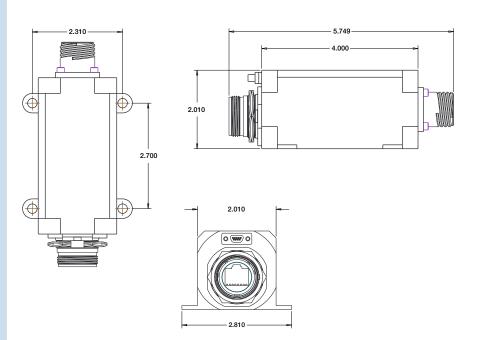
Amphenol Aerospace adds CTF-RJ45 to the CTF (Copper to Fiber) Media Converter Product Family. This product line utilizes standard fiber and copper connectors and contacts.

#### FIBER INTERFACE

- + Industry standard M29504 contacts
- + Also available in MT or ARINC-801 configuration
- + Multimode or Single Mode fiber
- + MM up to 500 m | SM up to 120 km
- + Standard MIL-DTL 38999 13-4 connector

#### COPPER INTERFACE

- + Compatible with Ethernet IEEE 802.3
- + Standard RJ45 interface
- + Standard MIL-DTL 38999 size 13 shell



CONTACT US: Jared Sibrava E-mail: jsibrava@amphenol-aao.com Phone: 607-643-1845

# Amphenol<sup>®</sup> Aerospace

PDS-271

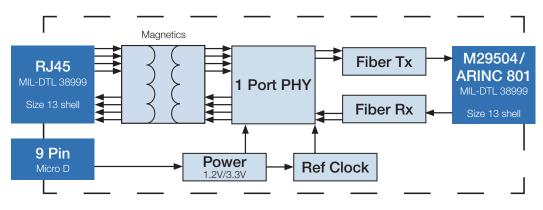
### When do you need CTF-RJ45?

Distance Comparison								
Copper			Fiber					
Standard	CAT 5	CAT 6a	850nm	1310nm	1550 nm			
1000 BASE T	100 m		500 m	10km	70km			
10GBASE T		100 m	300 m	10km	80-120km			

### Part Numbers:

Part Number	Copper Standard	Copper Connect	Fiber Standard	Media To	Wavelength
CF-020010-341	1000 BASE T	RJ45	1000BASE-LX/LH	SM	1310nm
CF-020010-342	1000 BASE T	RJ45	1000BASE-ZX	SM	1550nm
CF-020010-343	1000 BASE T	RJ45	1000BASE-SX	MM	850nm
CF-020010-344	10GBASE T	RJ45	10GBASE-LR	SM	1310nm
CF-020010-345	10GBASE T	RJ45	10GBASE-ER/ZR	SM	1550nm
CF-020010-346	10GBASE T	RJ45	10GBASE-SR	MM	850nm





CONTACT US: Jared Sibrava E-mail: jsibrava@amphenol-aao.com Phone: 607-643-1845



## Amphenol<sup>®</sup> Aerospace

PDS-271

#### Overview

Amphenol integrated electronic products are designed and manufactured to our Ruggedization guidelines listed below. These guidelines ensure years of reliable operation in harsh environment applications where extreme operating temperatures, shock, vibration and corrosive atmospheres are regularly experienced

#### Temperature

- Operating Temperature Thermal Cycles between -40°C and 85°C while device is operating
- Temperature is measured at chassis housing or card edge
- Storage Temperature Thermal Cycles between -55°C and 125°C

#### Humidity

- Operating Humidity Humidity cycle between 0-100% non-condensing humidity while device is operating
- Storage Humidity Humidity cycle between 0-100% condensing humidity

#### Sealing

• Sealing can be optionally provided at the MIL-DTL-38999 interface with up to 10-5 cc/sec performance

#### Fluids Susceptibility

• MIL-DTL-38999 receptacle interface per EIA-364-10E

#### Vibration & Shock

Sine Vibration – 10 g Peak, 5-2,000Hz

-Based on a sine sweep duration of 10 minutes per axis in each of three mutually perpendicular axes. May be displacement limited from 5 to 44 Hz, depending on specific test.

- Random Vibration 0.005@5Hz, 0.1@15Hz, 0.1@2,000Hz
  - -60 minutes per axis, in each of three mutually perpendicular axes.
- <u>40 G Peak Shock Cycle</u>

-Three hits in each axis, both directions, ½ sine and terminal-peak saw tooth, Total 36 hits.

#### Altitude

• -1,500 to 60,000 ft Altitude Testing w/ Rapid Depressurization

#### Electromagnetic Compatibility

• Designed to comply with MIL-STD-461E

#### Printed Circuit Board Assemblies

• Conformal Coat

-Amphenol performs Conformal Coating to both sides of printed circuit board assemblies using HUMISEAL IB31

- in accordance with IPC-610, Class 3.
  - Printed Circuit Board Rigidity
    - -Amphenol printed circuit boards are fabricated in accordance with IPC-6012, Class 3.
  - Printed Circuit Board Fabrication
    - -Amphenol printed circuit boards acceptance criteria is in accordance with IPC-610, Class 3.

#### **Reliability Predictions (MTBF)**

Amphenol can perform Mean Time Between Failure (MTBF) reliability analysis in full compliance with MIL-HDBK-217F-1 Parts Count Prediction and MIL-HDBK-217F-1 Parts Stress Analysis Prediction. We can also perform reliability analyses in full compliance of ANSI/VITA 51.1 if it is required or preferred over the later method.

#### CONTACT US:

Jared Sibrava

E-mail: jsibrava@amphenol-aao.com

Phone: 607-643-1845

Notice: Specifications are subject to change without notice. Contact your nearest Amphenol Corporation Sales Office for the latest specifications. All statements, information and data given herein are believed to be accurate and reliable but are presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements or suggestions concerning possible use of our products are made without representation or warranty that any such use is free of patent infringement and are not recommendations to infringe any patent. The user should assume that all safety measures are indicated or that other measures may not be required. Specifications are typical and may not apply to all connectors. AMPHENOL is a registered trademark of Amphenol Corporation. ©2015 Amphenol Corporation REV:1/28/2015